

MECHANICAL CASE OUTLINE

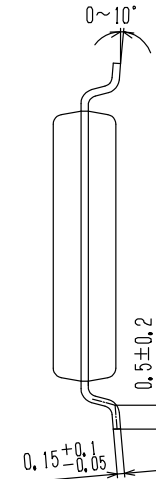
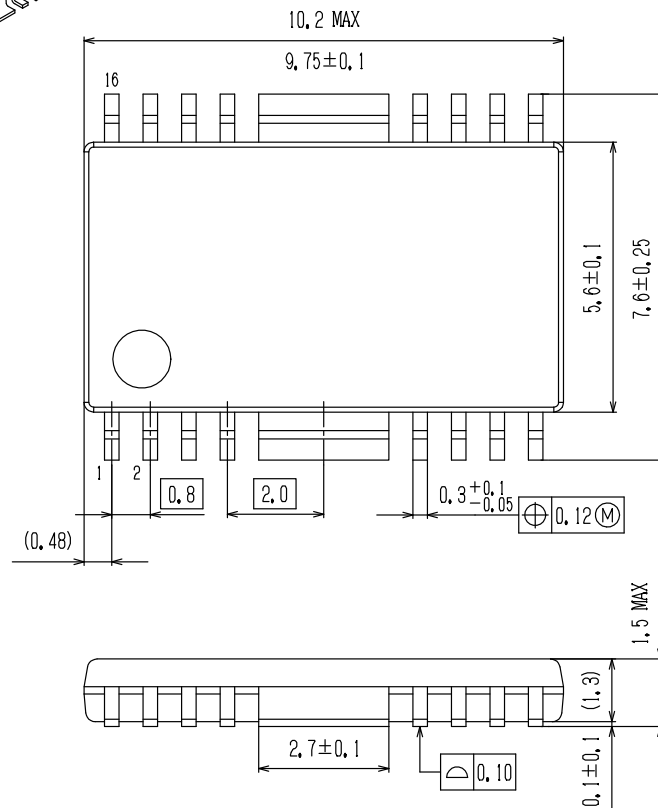
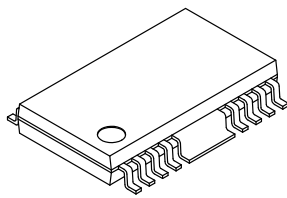
PACKAGE DIMENSIONS

ON Semiconductor®

ON

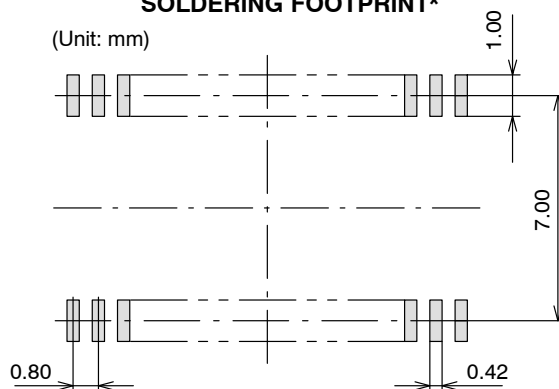
HSSOP16 (275 mil) CASE 943AF ISSUE A

DATE 25 OCT 2013



SOLDERING FOOTPRINT*

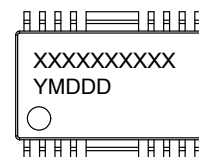
(Unit: mm)



NOTE: The measurements are not to guarantee but for reference only.
Land pattern design in Fin area to be altered in response to customers' individual application.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXXXX = Specific Device Code
Y = Year
M = Month
DDD = Additional Traceability Data

*This information is generic. Please refer to device data sheet for actual part marking.
Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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DESCRIPTION:	HSSOP16 (275 MIL)	PAGE 1 OF 1

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